provide an electronic device or an electronic appliance containing the composition.

Solution to Problem

[0009]

One aspect of the invention relates to an underfill sealant composition comprising: (a) 20-60% of a (meth)acrylic compound; (b) 1-20% of a maleimide compound wherein the maleimide compound (b) comprises a bismaleimide; (c) 1-20% of an isocyanuric acid having an allyl group; (d) 0.1-5% of a radical initiator; and (e) 10-80% of a filler, wherein all % are based on the total weight of the composition.

Another aspect relates to an underfill sealant composition comprising: (a) 20-60% of a (meth)acrylic compound; (b) 1-20% of a maleimide compound wherein the maleimide compound (b) comprises a bismaleimide; (c) 0.001-20% of an isocyanuric acid having an allyl group; (d) 0.1-5% of a radical initiator; and (e) 10-80% of a filler, wherein all % are based on the total weight of the composition.

The present ~~invention~~ disclosure further relates to the following items.

[0010]

1. An underfill sealant composition comprising:
(a) a (meth)acrylic compound and
(c) an isocyanuric acid having an allyl group.

[0011]

2. The composition according to the above item 1, further comprising (b) a maleimide compound.

[0012]

3. The composition according to the above item 2, wherein the maleimide compound (b) comprises a bismaleimide.

[0013]

4. The composition according to any one of the above items 1 to 3, further comprising a radical initiator.

[0014]

5. The composition according to any one of the above items 1 to 4 comprising:
10-90 wt% of the (meth)acrylic compound (a) based on the total weight of the composition and
0.001-20 wt% of the isocyanuric acid having an allyl group (c) based on the

total weight of the composition.

[0015]

6. The composition according to any one of the above items 2 to 5, comprising 0.1-50 wt% of the maleimide compound (b) based on the total weight of the composition.

[0016]

7. The composition according to any one of the above items 1 to 6, which is used in flip chip mounting.

[0017]

8. An electronic device comprising a cured product of the composition according to any one of the above items 1 to 7.

[0018]

CLAIMS

1. An underfill sealant composition comprising:
(a) a (meth)acrylic compound and
(c) an isocyanuric acid having an allyl group.

2. The composition according to Claim 1, further comprising (b) a maleimide compound.

3. The composition according to Claim 2, wherein the maleimide compound (b) comprises a bismaleimide.

4. The composition according to any one of Claims 1 to 3, further comprising a radical initiator.

5. The composition according to any one of Claims 1 to 4 comprising:
10-90 wt% of the (meth)acrylic compound (a) based on the total weight of the composition and
0.001-20 wt% of the isocyanuric acid having an allyl group (c) based on the total weight of the composition.

6. The composition according to any one of Claims 2 to 5, comprising 0.1-50 wt% of the maleimide compound (b) based on the total weight of the composition.

7. The composition according to any one of Claims 1 to 6, which is used in flip chip mounting.

8. An electronic device comprising a cured product of the composition according to any one of Claims 1 to 7.

9. An electronic appliance comprising the electronic device according to Claim 8.

CLAIMS

1. An underfill sealant composition comprising:
   (a) 20-60% of a (meth)acrylic compound;
   (b) 1-20% of a maleimide compound wherein the maleimide compound (b) comprises a bismaleimide;
   (c) 1-20% of an isocyanuric acid having an allyl group;
   (d) 0.1-5% of a radical initiator; and
   (e) 10-80% of a filler,
   wherein all % are based on the total weight of the composition.

2. An underfill sealant composition comprising:
   (a) 20-60% of a (meth)acrylic compound;
   (b) 1-20% of a maleimide compound wherein the maleimide compound (b) comprises a bismaleimide;
   (c) 0.001-20% of an isocyanuric acid having an allyl group;
   (d) 0.1-5% of a radical initiator; and
   (e) 10-80% of a filler,
   wherein all % are based on the total weight of the composition.

3. The composition according to Claims 1 or 2, which is used in flip chip mounting.

4. An electronic device comprising a cured product of the composition according to any one of Claims 1 to 3.

5. An electronic appliance comprising the electronic device according to Claim 4.